



Advance Product Change Notification

201909001A

Issue Date: 16-Sep-2019

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For detailed information we invite you to view this notification online

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QUALITY

Management Summary

SOT886 assembly and test will be transferred from ATGD and ATSN to ATBK. This streamlines manufacturing flow and improves package reliability with introduction of roughened leadframe and Cu wire.

Change Category

- | | | | | |
|--|--|---|--|---|
| <input type="checkbox"/> Wafer Fab Process | <input checked="" type="checkbox"/> Assembly Process | <input type="checkbox"/> Product Marking | <input checked="" type="checkbox"/> Test Location | <input type="checkbox"/> Design |
| <input type="checkbox"/> Wafer Fab Materials | <input checked="" type="checkbox"/> Assembly Materials | <input type="checkbox"/> Mechanical Specification | <input type="checkbox"/> Test Process | <input type="checkbox"/> Errata |
| <input type="checkbox"/> Wafer Fab Location | <input checked="" type="checkbox"/> Assembly Location | <input checked="" type="checkbox"/> Packing/Shipping/Labeling | <input checked="" type="checkbox"/> Test Equipment | <input type="checkbox"/> Electrical spec./Test coverage |
| <input type="checkbox"/> Firmware | <input type="checkbox"/> Other | | | |

XSON6 (SOT886) Assembly/Test Transfer from ATGD and ATSN to ATBK

Description of Change

NXP Semiconductors is transferring assembly and test of the SOT886 (XSON6) package from ATSN and ATGD to ATBK. Standard ATBK BOM and flows will be used.

Product data sheets will be updated with new orderable part numbers to reflect the use of Static Shielding Bags (SSB). Orderable Part #s/12NC will be included in update of Final PCN.

Reason for Change

Move production to an NXP facility to assure product quality and delivery.

Identification of Affected Products

Packing Labels will show Product Manufacturing Code (PMC) "n" to reflect ATBK assembly.

Product Availability

Sample Information

Samples are available from 16-Sep-2019
Samples available per attached schedule.

Production

Shipment dates are product specific, see attached plan

Anticipated Impact on Form, Fit, Function, Reliability or Quality

No impact on form, fit, function, reliability or quality.

Data Sheet Revision

A new datasheet will be issued

Disposition of Old Products

Existing inventory will be shipped until depleted

Timing and Logistics

The Self Qualification Report will be ready on 06-Sep-2019.

The Final PCN is planned to be issued on: 20-Sep-2019.

In compliance with JEDEC J-STD-046, your acknowledgement of this change is expected by 16-Oct-2019.

A final PCN will be issued that will include datasheets (including orderable part #s) and updates to projected release dates.

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

At NXP Semiconductors we are constantly striving to improve our product and processes to ensure they reach the highest possible Quality Standards.

Customer Focus, Passion to Win.

NXP Quality Management Team.

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NXP Semiconductors

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Affected Part Numbers

NX3L1G3157GM,115

NCX2200GM,115

NX3L1T3157GM,115

NX3L1G66GM,115

Affected 12NC

935284122115

935294048115

935285418115

935284123115